

#### Discription

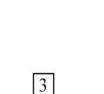
The HGSOT08C-HE3-18 protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect 2 unidirectional line in applications where arrays are not practical.

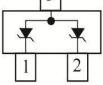
#### Features

- ★ Transient protection for high-speed data lines IEC 61000-4-2(ESD) ±30kV (Contact) ±30kV (Air)
- IEC 61000-4-4(EFT) 40A (5/50 ns) ★ Peak power dissipation: 350W (8/20us)
- ★ Working voltages : 8V
- Protects one bidirectional line or two unidirectional lines
- ★ Low clamping voltage
- ★ Low leakage current

## Orderingin formation



SOT-23

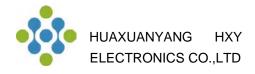


Circuit Diagram

Product ID	Pack	Qty(PCS)
HGSOT08C-HE3-18	SOT-23	3000

## Absolute Ratings(Tamb = 25°C)

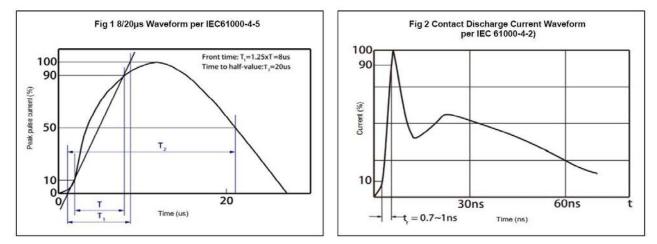
Symbol	Parameter	Value	Units	
P <sub>PP</sub>	Peak Pulse Power ( $t_p = 8/20 \ \mu \ s$ )		350	W
TL	Maximum lead temperature for soldering during 10s		260	°C
T <sub>stg</sub>	Storage Temperature Range		-55 to +155	°C
T <sub>op</sub>	Operating Temperature Range		-40 to +125	°C
Tj	Maximum junction temperature		150	°C
	IEC61000-4-2 (ESD) air discha contact discha	•	±30 ±30	KV
	IEC61000-4-4 (EFT)		40	А



## **Electrical Characteristics**

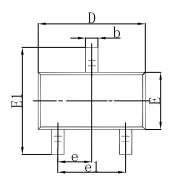
Symbol	Parameter	Test Condition	Min	Тур	Max	Units
Vrwm	Reverse Working Voltage				8.0	V
Vbr	Reverse Breakdown Voltage	l⊤ = 1mA	8.5			V
IR	Reverse Leakage Current	$V_{RWM} = 8.0V$			2	μA
Vc	Clamping Voltage	I <sub>RWM</sub> = 1A, t <sub>P</sub> = 8/20μs			13.4	V
	Clamping Voltage	I <sub>RWM</sub> = 15А, t <sub>P</sub> = 8/20µs			24	V
CJ	Junction Capacitance	$V_R = 0V, f = 1MHz$		170	200	pF

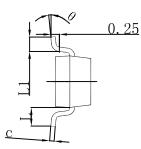
# **Typical Characteristics**

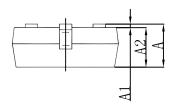




## **SOT-23 Package Outline Dimensions**

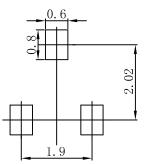






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
e	0.950 TYP		0.037	0.037 TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

# SOT-23 Suggested Pad Layout



Note:

1.Controlling dimension: in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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